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Form PTO-1449 (modified)	Atty. Docket No. 2000.112000/DE0454	Serial No. 10/677,911
List of Patents and Publications for Applicant's INFORMATION DISCLOSURE STATEMENT (Use several sheets if necessary)	Applicant Moritz Andreas Meyer, Ehrenfried Zschech and Eckhard Langer	
	Filing Date: October 2, 2004	Group: 2881

U.S. Patent Documents	Foreign Patent Documents	Other Art
See Page 1	*See Page 1*	*See Page 1*

U.S. Patent Documents

Exam. Init.	Ref. Des.	Document Number	Date	Name	Class	Sub Class	Filing Date of App.
MM	A1	5,124,645	6/23/92	Rhoden *et al.*	324	158F	
	A2						
	A3						
	A4						
	A5						

Foreign Patent Documents

Exam. Init.	Ref. Des.	Document Number	Date	Country	Class	Sub Class	Translation Yes/No
	B1						
	B2						
	B3						

Other Art (Including Author, Title, Date Pertinent Pages, Etc.)

Exam. Init.	Ref. Des.	Citation
MM	C1	Lau *et al.*, "*In situ* electron microscopy studies of electromigration in stacked Al(Cu)/Tin interconnects," *Applied Physics Letters*, 76:164-66, 2000
MM	C2	Meyer *et al.*, "*In situ* SEM observation of electromigration phenomena in fully embedded copper interconnect structures," *Microelectronic Engineering*, 64:375-82, 2002
MM	C3	Schneider *et al.*, "Electromigration in passivated Cu interconnects studied by transmission x-ray microscopy," *J. Vac. Sci. Technol.*, 20:3089-94, 2002
MM	C4	Xu *et al.*, "Quantitative metrology study of Cu/SiO_2 interconnect structures using fluorescence x-ray microscopy," *Applied Physics Letters*, 78:820-22, 2001

EXAMINER: Melissa Walls | DATE CONSIDERED: January 11, 2005

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